

Title (en)

DEVICE AND METHOD FOR ELECTROPLATING SUBSTRATES IN PROCESS CHAMBERS

Title (de)

VORRICHTUNG UND VERFAHREN ZUM GALVANISIEREN VON SUBSTRATEN IN PROZESSKAMMERN

Title (fr)

PROCÉDÉ ET DISPOSITIF DE GALVANISATION DE SUBSTRATS DANS DES CHAMBRES DE TRAITEMENT

Publication

EP 2331733 A2 20110615 (DE)

Application

EP 09777348 A 20090721

Priority

- EP 2009005301 W 20090721
- DE 102008045260 A 20080901

Abstract (en)

[origin: DE102008045260B3] Apparatus for galvanizing one side of a substrate, in a processing chamber with anodes (6) and circulating electrolyte (8), has a component (2) consisting of an anode support (3) for receiving soluble anode material (or an insoluble anode), a central free space (3) and (as upper part) operating device(s) (5) for adjusting shut-off of electrolyte flow through the chamber via the anode support and free space. Apparatus for galvanizing one side of a substrate, in a processing chamber with soluble or insoluble anodes (6) and an electrolyte (8) circulating through the chamber, has a component (2) consisting of an anode support (3) for receiving soluble anode material (or an insoluble anode) and having a central free space (3). The electrolyte-permeable upper part of the component consists of operating device(s) (5) for adjusting shut-off of the flow of electrolyte through the chamber via the anode support and free space. An independent claim is included for a corresponding galvanization method using the apparatus, in which varying current conditions are set on the surface to be electrochemically treated during galvanization of the article and demetallization of the article support, by variation of the volume flow of the circulating electrolyte (8) and by constructional features of the component (2).

IPC 8 full level

C25D 17/12 (2006.01); **C25D 17/00** (2006.01); **C25D 17/02** (2006.01); **H01L 31/18** (2006.01); **H05K 3/24** (2006.01)

CPC (source: EP US)

C25D 5/08 (2013.01 - EP US); **C25D 17/001** (2013.01 - EP); **C25D 17/002** (2013.01 - EP); **C25D 17/007** (2013.01 - EP US); **C25D 17/008** (2013.01 - EP); **C25D 17/12** (2013.01 - EP); **C25D 17/02** (2013.01 - EP); **C25D 21/10** (2013.01 - EP)

Citation (search report)

See references of WO 2010022825A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

Designated extension state (EPC)

AL BA RS

DOCDB simple family (publication)

DE 102008045260 B3 20090910; **DE 102008045260 B8 20100211**; EP 2331733 A2 20110615; WO 2010022825 A2 20100304; WO 2010022825 A3 20100514

DOCDB simple family (application)

DE 102008045260 A 20080901; EP 09777348 A 20090721; EP 2009005301 W 20090721